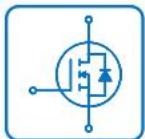




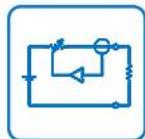
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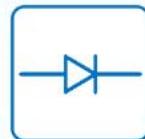
TVS



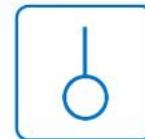
MOS



LDO



Diode



Sensor



DC-DC

Product Specification

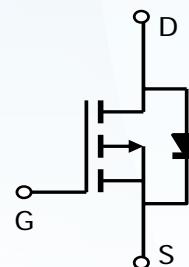
▶ Domestic Part Number	AO4411
▶ Overseas Part Number	AO4411
▶ Equivalent Part Number	AO4411



30V P-Channel MOSFET

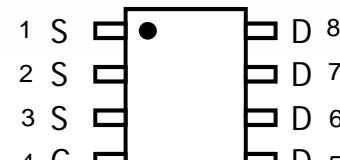
General Description

The AO4411 uses advanced trench technology to provide excellent $R_{DS(ON)}$, and ultra-low low gate charge. This device is suitable for use as a load switch or in PWM applications.



Product Summary

V_{DS}	-30V
I_D (at $V_{GS}=-10V$)	-8A
$R_{DS(ON)}$ (at $V_{GS}=-10V$)	< 32mΩ
$R_{DS(ON)}$ (at $V_{GS} = -4.5V$)	< 55mΩ



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Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum		Units
Drain-Source Voltage	V_{DS}	-30		V
Gate-Source Voltage	V_{GS}	± 20		V
Continuous Drain Current ^A	I_D	-8		A
$T_A=70^\circ C$		-6.6		
Pulsed Drain Current ^B	I_{DM}	-40		
Power Dissipation ^A	P_D	3		W
$T_A=70^\circ C$		2.1		
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150		°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	24	40	°C/W
Steady-State		54	75	°C/W
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	21	30	°C/W
Steady-State				

30V P-Channel MOSFET

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}, V_{GS}=0\text{V}$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-24\text{V}, V_{GS}=0\text{V}$	$T_J=55^\circ\text{C}$	-1	-5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm20\text{V}$			±100	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.2	-2	-2.4	V
$I_{D(\text{ON})}$	On state drain current	$V_{GS}=-10\text{V}, V_{DS}=-5\text{V}$	-40			A
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}, I_D=-8\text{A}$		24.5	32	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-5\text{A}$		41	55	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}, I_D=-8\text{A}$		14.5		S
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}, V_{GS}=0\text{V}$		-0.76	-1	V
I_S	Maximum Body-Diode Continuous Current				-4.2	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=-15\text{V}, f=1\text{MHz}$		920	1120	pF
C_{oss}	Output Capacitance			190		pF
C_{rss}	Reverse Transfer Capacitance			122		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		3.6	5	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge (10V)	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, I_D=-8\text{A}$		18.4	23	nC
$Q_g(4.5\text{V})$	Total Gate Charge (4.5V)			9.3	11.5	nC
Q_{gs}	Gate Source Charge			2.7		nC
Q_{gd}	Gate Drain Charge			4.9		nC
$t_{D(\text{on})}$	Turn-On Delay Time	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, R_L=1.8\Omega, R_{\text{GEN}}=3\Omega$		7.1		ns
t_r	Turn-On Rise Time			3.4		ns
$t_{D(\text{off})}$	Turn-Off Delay Time			18.9		ns
t_f	Turn-Off Fall Time			8.4		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-8\text{A}, dI/dt=100\text{A}/\mu\text{s}$		21.5	27	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-8\text{A}, dI/dt=100\text{A}/\mu\text{s}$		12.5		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $\leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80 μs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

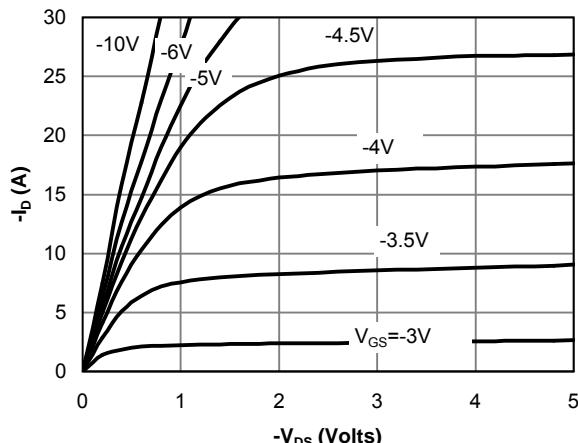


Fig 1: On-Region Characteristics

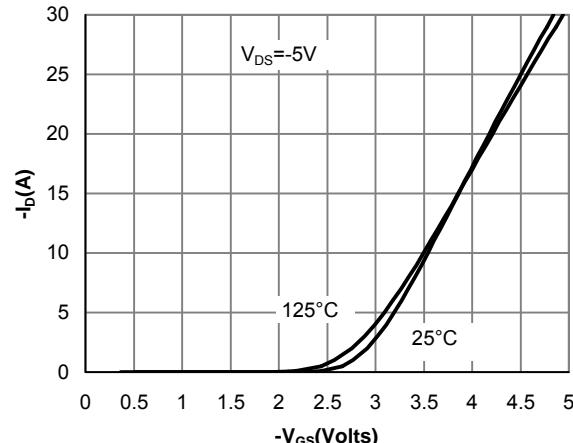


Figure 2: Transfer Characteristics

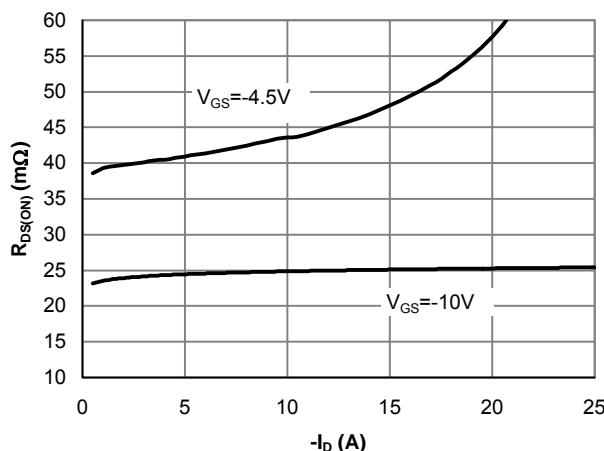


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

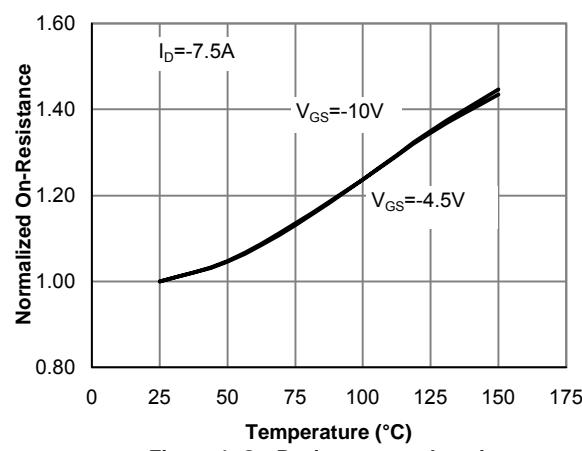


Figure 4: On-Resistance vs. Junction Temperature

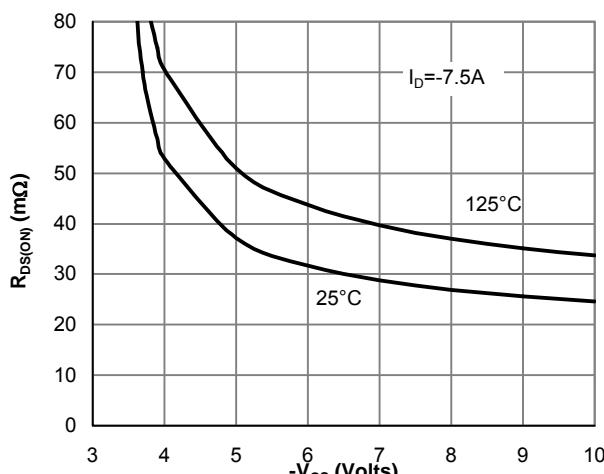


Figure 5: On-Resistance vs. Gate-Source Voltage

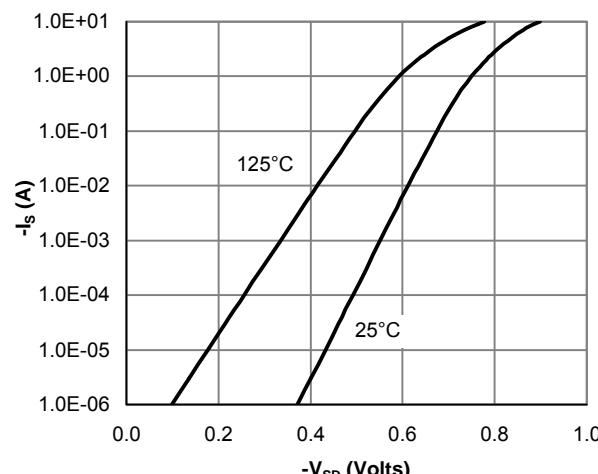
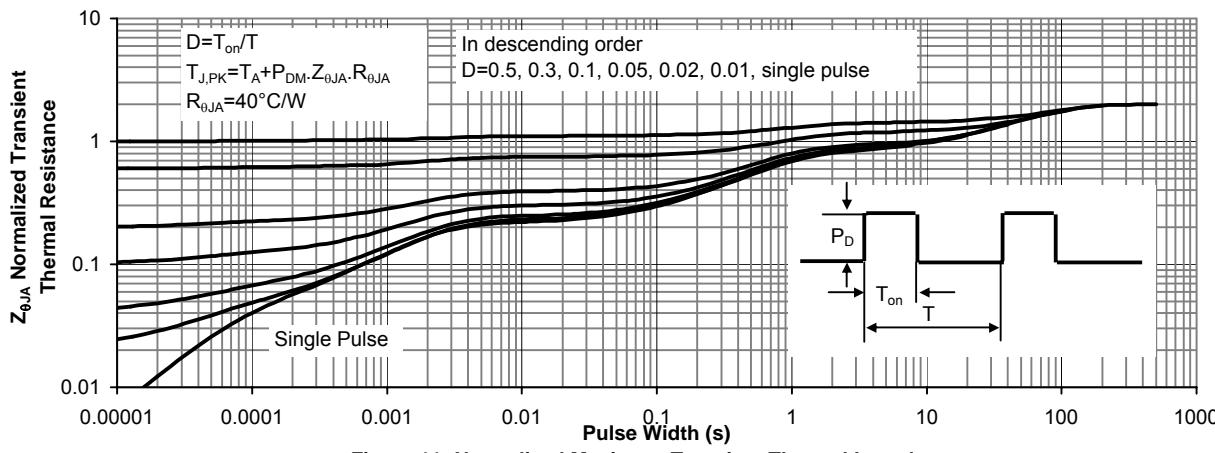
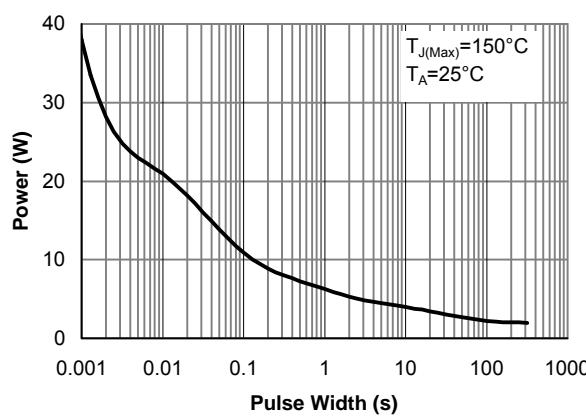
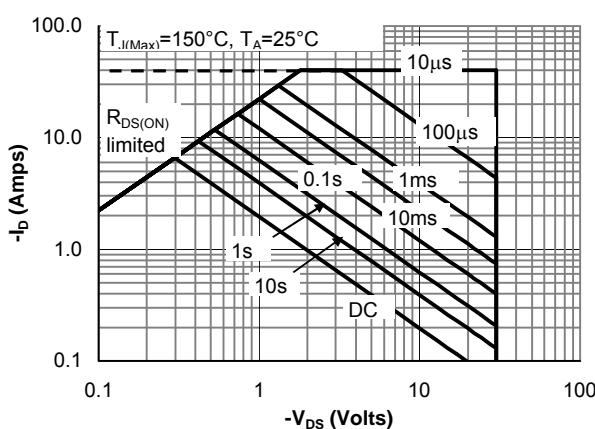
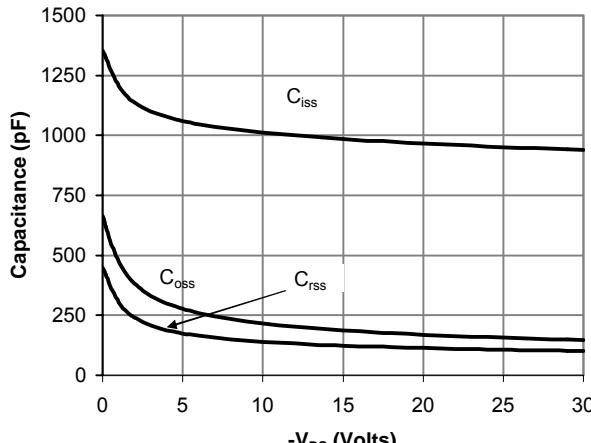
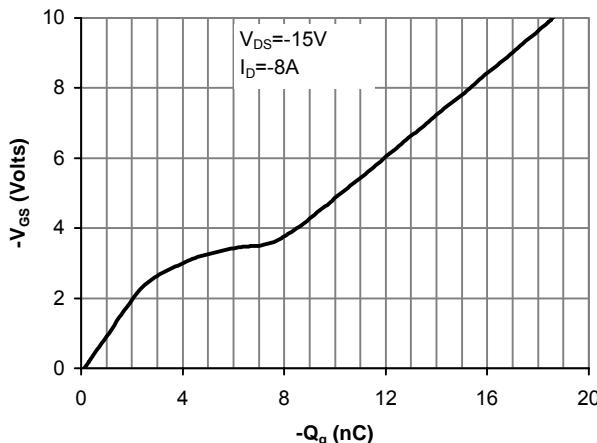


Figure 6: Body-Diode Characteristics

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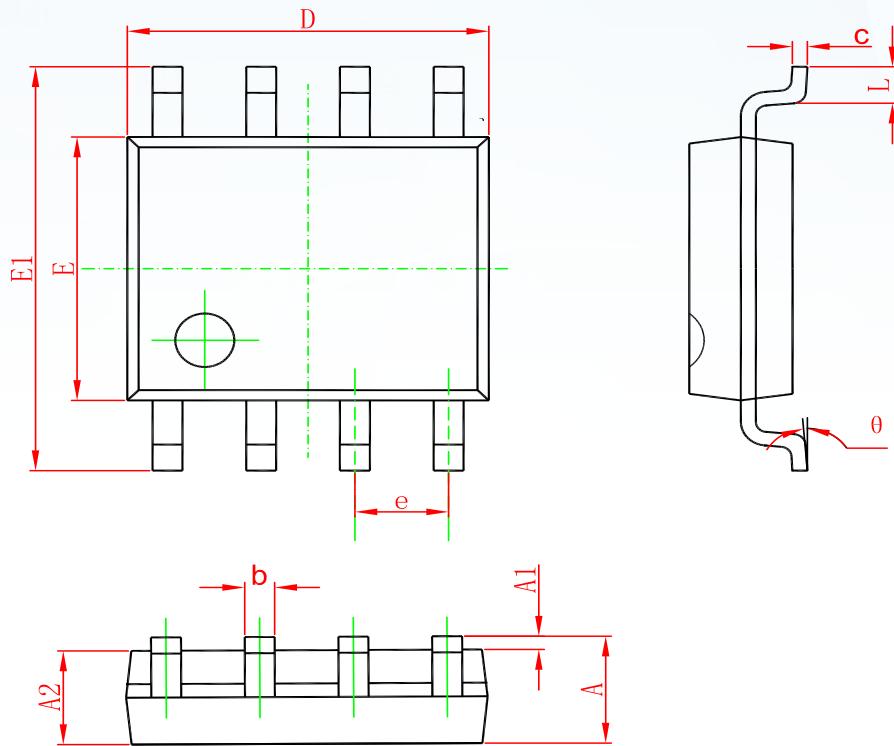
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



30V P-Channel MOSFET

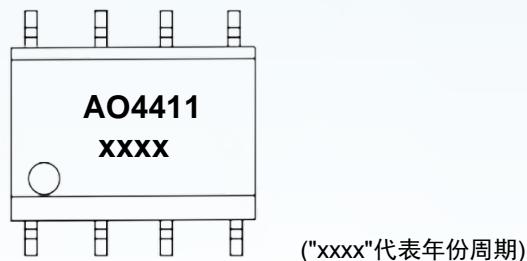
PACKAGE OUTLINE DIMENSIONS

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Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

30V P-Channel MOSFET

Marking**Ordering information**

Order code	Package	Baseqty	Deliverymode
AO4411	SOP-8	3000	Tape and reel

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